Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	7 X 7 X 0.75 (5.1 EP)
Lead Count	48
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.78E-02	86.91	869100	28.94	289358
Thermosets	Epoxy & Phenol Resin	Proprietary	5.56E-03	12.78	127800	4.25	42550
Other inorganic materials	Carbon black	1333-86-4	1.35E-04	0.31	3100	0.10	1032
Subtotal			4.35E-02	100.00	1000000	33.29	332940

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.60 E-02	97.5	975000	58.16	581608
Copper & its alloys	Iron	7439-89-6	1.83 E-03	2.35	23500	1.40	14018
Copper & its alloys	Zinc	7440-66-6	9.35 E-05	0.12	1200	0.07	716
Copper & its alloys	Phosphorus	7723-14-0	2.34 E-05	0.03	300	0.02	179
Subtotal			7.79 E-02	100.00	1000000	59.65	596521

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.60 E-04	100.0	1000000	0.35	3522

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.90 E-03	100.0	1000000	2.22	22201

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.94 E-04	99.0	990000	0.45	4547
Precious metals	Palladium	7440-05-3	6.00 E-06	1.0	10000	0.00	46
Subtotal			6.00 E-04	100.0	1000000	0.46	4593

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.60 E-03	100.0	1000000	2.76	27560

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.22 E-03	73.40	734000	0.93	9328
Thermoset	Epoxy Resin	Proprietary	3.05 E-04	18.35	183500	0.23	2332
Other inorganic materials	Metal oxide	Proprietary	4.57 E-05	2.75	27500	0.03	349
Others	Curing and hardening agent	Proprietary	4.57 E-05	2.75	27500	0.03	349
Other organic materials	Gamma Butyrolactone	96-48-0	4.57 E-05	2.75	27500	0.03	349
Subtotal			1.66 E-03	100.0	972500	1.24	12708

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.31 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES